

TERMINAL PAD SOLDERABILITY:
 Meets EIA Specification RS186-9E
 And ANSI/J-STD-002 Category 3.

TERMINAL PAD MATERIALS:

Tin-Plated Nickel-Copper
 Lead-Free, ROHS Compliant

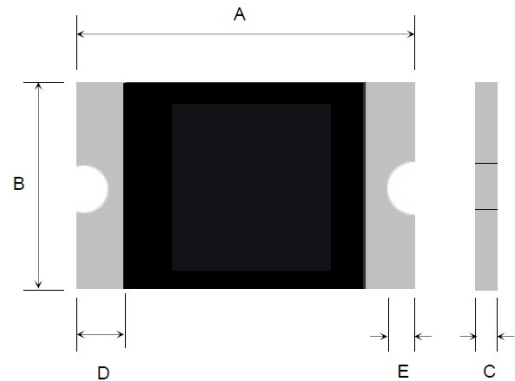


TABLE I. DIMENSIONS:

Unit: mm

| Model | A | | B | | C | | D | E |
|--------------|------|------|------|------|------|------|------|------|
| | Min | Max | Min | Max | Min | Max | Min | Min |
| 1812-150,16V | 4.37 | 4.73 | 3.07 | 3.41 | 0.40 | 0.90 | 0.30 | 0.25 |

TABLE II. PERFORMANCE RATINGS:

| Model | Vmax | I _{max} | I _{hold@25°C} | I _{trip@25°C} | P _d Typ. | Maximum Time TO Trip | | Resistance | |
|--------------|-------|------------------|------------------------|------------------------|---------------------|----------------------|------------|-----------------------|-----------------------|
| | (Vdc) | (A) | (A) | (A) | (W) | Current (A) | Time (Sec) | R _{imin} (Ω) | R _{imax} (Ω) |
| 1812-150,16V | 16.0 | 100 | 1.50 | 3.00 | 0.8 | 8.0 | 0.50 | 0.040 | 0.160 |

Note:

I_{hold}=Hold current: maximum current device will pass without tripping in 23°C still air.

I_{trip}=Trip current: minimum current at which the device will trip in 23°C still air.

V_{max}=Maximum voltage device can withstand without damage at rated current (I_{max}).

I_{max}=Maximum fault current device can withstand without damage at rated voltage (V_{max}).

P_d=Power dissipated from device when in the tripped state at 23°C still air.

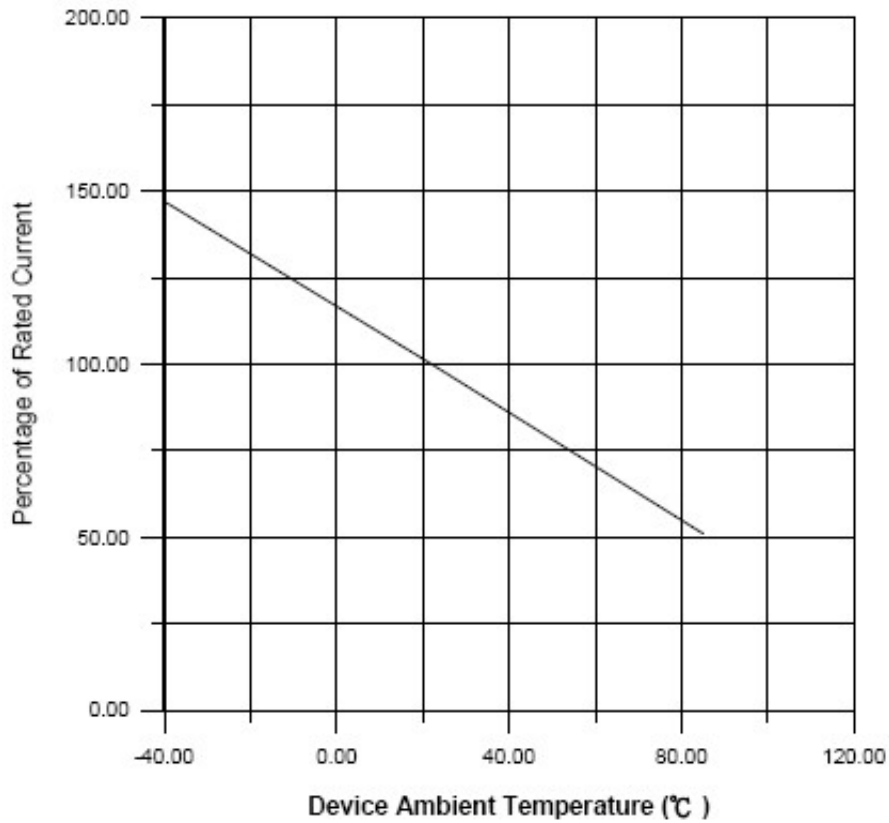
R_{imin}=Minimum resistance of device in initial (un-soldered) state.

R_{imax}=Maximum resistance of device at 23°C measured one hour after tripping or reflow soldering of 260°C for 20sec.

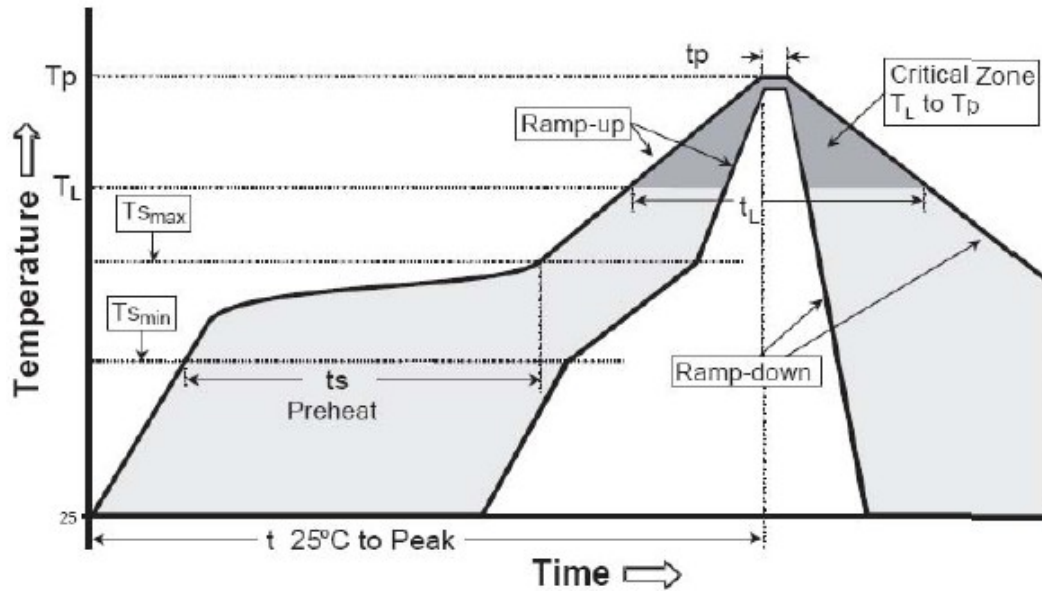
**THERMAL DERATING CHART FOR SMD1812 SERIES-IHOLD(Amps)
RECOMMENDED DATA**

| Model | Ambient Operation Temperature | | | | | | | | |
|--------------|-------------------------------|------|------|------|------|------|------|------|------|
| | -40℃ | -20℃ | 0℃ | 23℃ | 40℃ | 50℃ | 60℃ | 70℃ | 85℃ |
| 1812-150,16V | 2.28 | 2.03 | 1.75 | 1.50 | 1.21 | 1.07 | 0.93 | 0.79 | 0.58 |

THERMAL DERATING CURVE FOR SMD1812 SERIES



SOLDER REFLOW



RECOMMENDED CONCITIONS

| Profile Feature | Pd-Free Assembly |
|--|---------------------------------|
| Average Ramp-Up Rate(Tsmax to Tp) | 3°C/second max |
| Preheat —Temperature Min(Tsmin) —Temperature Max(Tsmax) —Time(Tsmin to Tsmax) | 150°C 200°C 60-180seconds |
| Time maintained above: —Temperature(TL) —Time(tL) | 217°C 60-150seconds |
| Peak Temperature(Tp) | 260°C |
| Time within 5°C of actual Peak Temperature(tp) | 20-40seconds |
| Ramp-Down Rate | 6°C/second max. |
| Time 25°C to Peak Temperature | 8minutes max. |
| Storage Condition | 0°C~35°C, ≤70%RH |

Note: 1.All temperature refer to topside of the package, measured on the package body surface.
2.If reflow temperature exceed the recommended profile, devices

PACKAGING

| Part Number | Component Package | Quantity |
|--------------|-------------------|----------|
| 1812-150,16V | 1812 | 1500 |

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